

LN2506DT1G

S-LN2506DT1G

30V N-Channel Enhancement-Mode MOSFET

1. FEATURES

- $V_{DS} = 30V$
- $R_{DS(ON)}, V_{GS}@10V, I_{DS}@5.8A = 41m\Omega$
- $R_{DS(ON)}, V_{GS}@4.5V, I_{DS}@5.0A = 45m\Omega$
- $R_{DS(ON)}, V_{GS}@2.5V, I_{DS}@2.0A = 90m\Omega$
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

2. APPLICATIONS

- Advanced trench process technology
- High density cell design for ultra low on-resistance

3. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LN2506DT1G	3B	4000/Tape&Reel

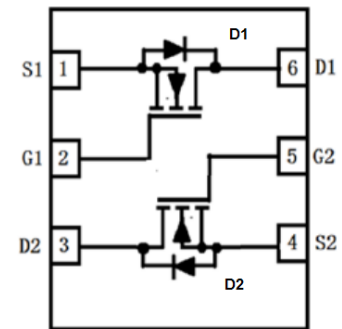
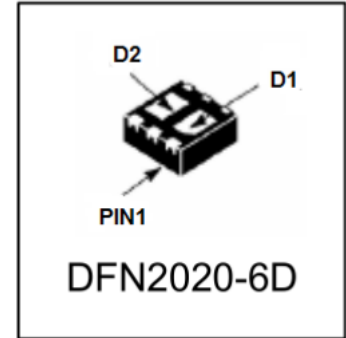
4. MAXIMUM RATINGS($T_a = 25^\circ C$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 12	V
Drain Current			A
– Continuous $T_a = 25^\circ C$	I_D	5.8	
– Pulsed(Note 1)	I_{DM}	30	

5. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Maximum Power Dissipation	PD	1.4	W
Thermal Resistance, Junction-to-Ambient(Note 2)	$R_{\theta JA}$	140	$^\circ C/W$
Junction and Storage temperature	T_J, T_{stg}	$-55 \sim +150$	$^\circ C$

1. Repetitive Rating: Pulse width limited by the Maximum junction temperature.
2. 1-in² 2oz Cu PCB board.



6. ELECTRICAL CHARACTERISTICS (Ta= 25°C)
OFF CHARACTERISTICS

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain–Source Breakdown Voltage (VGS = 0, ID = 250μA)	V(BR)DSS	30	-	-	V
Zero Gate Voltage Drain Current (VDS=30V, VGS=0V)	IDSS	-	-	1	μA
Gate–Body Leakage Current, Forward (VDS = 0 V, VGS = 12 V)	IGSSF	-	-	100	nA
Gate–Body Leakage Current, Reverse (VDS = 0 V, VGS = -12 V)	IGSSR	-	-	-100	nA
Forward Transconductance (VDS = 5.0 V, ID = 5 A)	gfs	10	15	-	S

ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage (VDS = VGS, ID = 250μA)	VGS(th)	0.7	-	1.4	V
Static Drain–Source On–State Resistance (VGS = 10 V, ID = 5.8 A) (VGS = 4.5 V, ID = 5 A) (VGS = 2.5 V, ID = 2 A)	RDS(on)	- - -	31 34 45	41 45 90	mΩ

DYNAMIC CHARACTERISTICS

Total Gate Charge (VGS = 4.5 V, ID = 5.8A, VDS= 15 V)	Qg	-	11	22	nC
Gate–Source Charge (VGS = 4.5 V, ID = 5.8A, VDS= 15 V)	Qgs	-	1.6	-	nC
Gate–Drain Charge (VGS = 4.5 V, ID = 5.8A, VDS= 15 V)	Qgd	-	2.8	-	nC
Input Capacitance (VGS = 0 V, f = 1.0MHz, VDS= 15 V)	Ciss	-	513.51	-	pF
Output Capacitance (VGS = 0 V, f = 1.0MHz, VDS= 15 V)	Coss	-	80.85	-	pF
Reverse Transfer Capacitance (VGS = 0 V, f = 1.0MHz, VDS= 15 V)	Crss	-	54.87	-	pF

SWITCHING CHARACTERISTICS

Turn-On Delay Time	(VDD = 15V, RL = 2.7Ω ID = 1A, VGEN = 10V, RG = 3Ω)	td(on)	-	7	14	ns
Rise Time		tr	-	15	30	
Turn-Off Delay Time		td(off)	-	38	76	
Fall Time		tf	-	3	6	

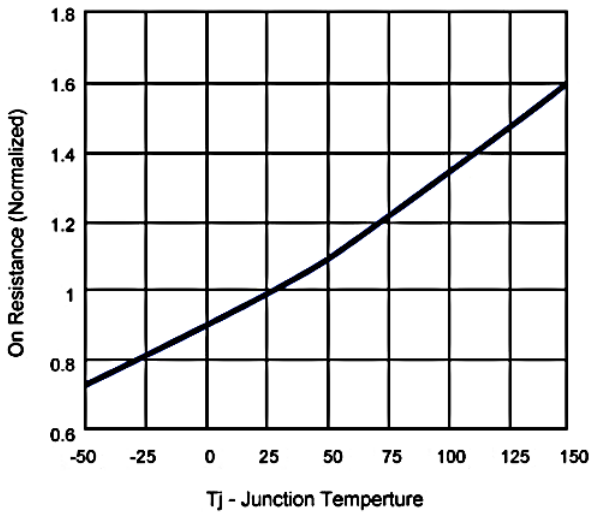
SOURCE–DRAIN DIODE CHARACTERISTICS

Forward Voltage (VGS = 0 V, ISD = 3 A)	VSD	-	-	1.2	V
Max. Diode Forward Current	IS	-	-	2.5	A

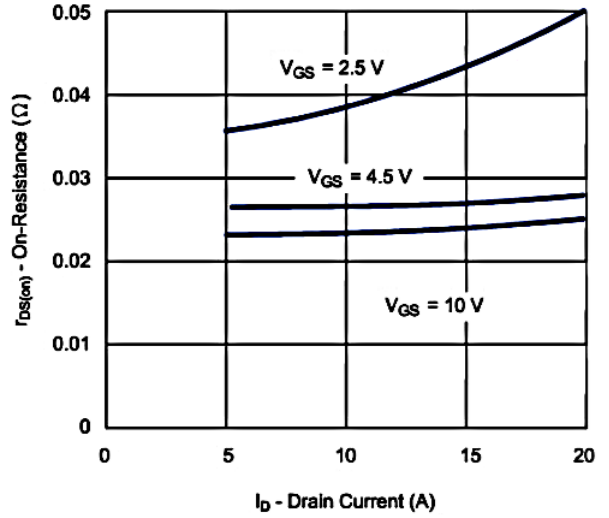
3. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

7. ELECTRICAL CHARACTERISTICS CURVES

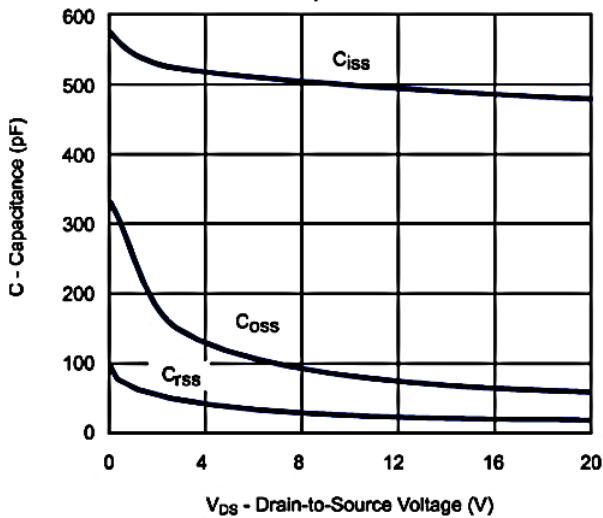
On Resistance vs. Junction Temperature



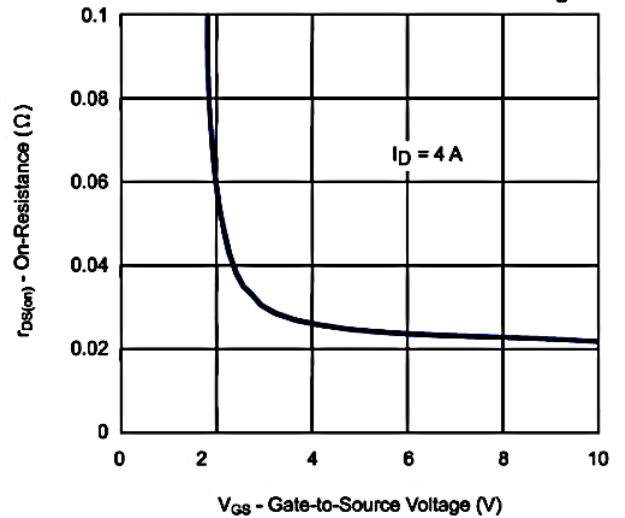
On-Resistance vs. Drain Current



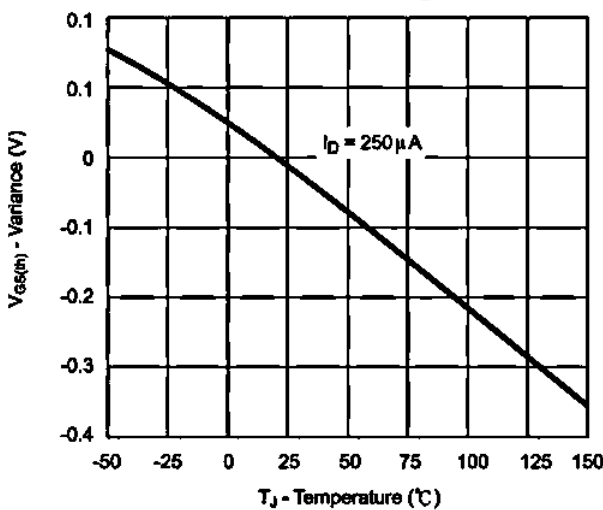
Capacitance



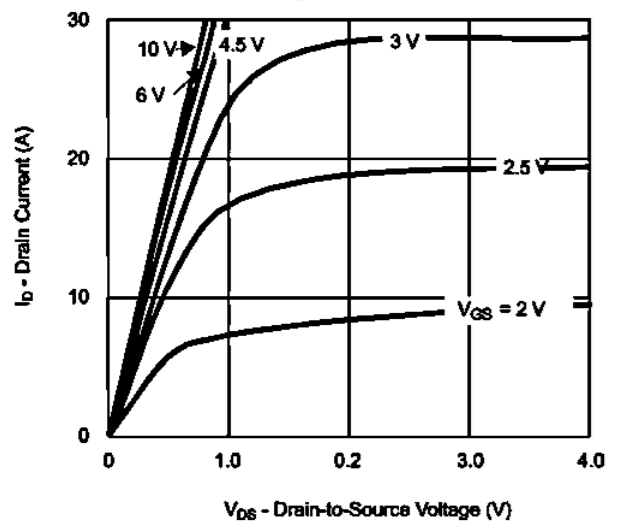
On-Resistance vs. Gate-to-Source Voltage



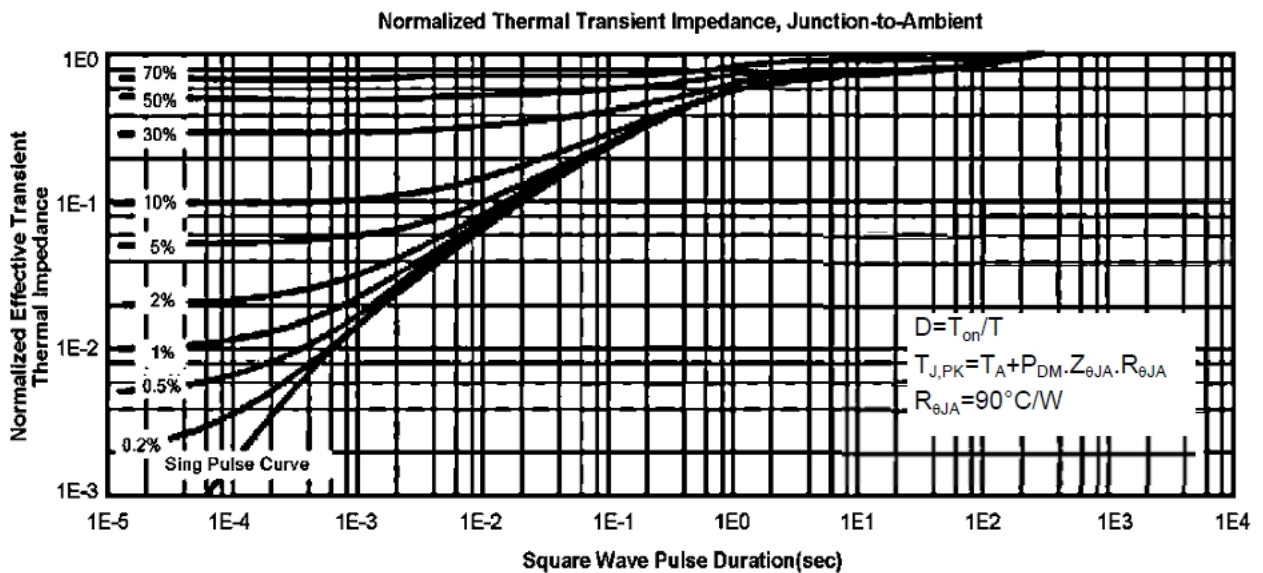
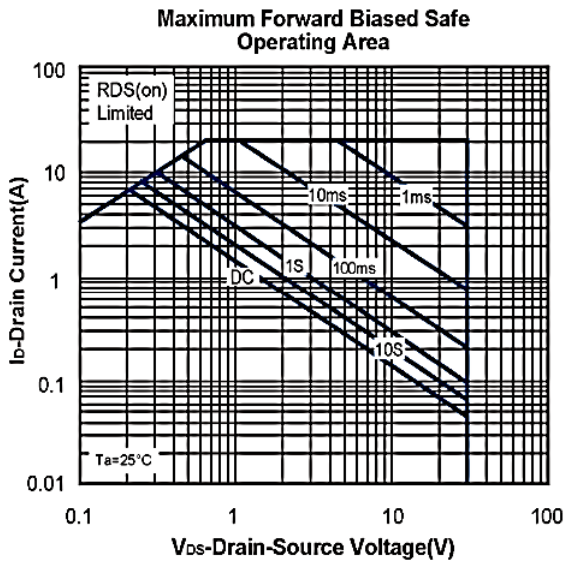
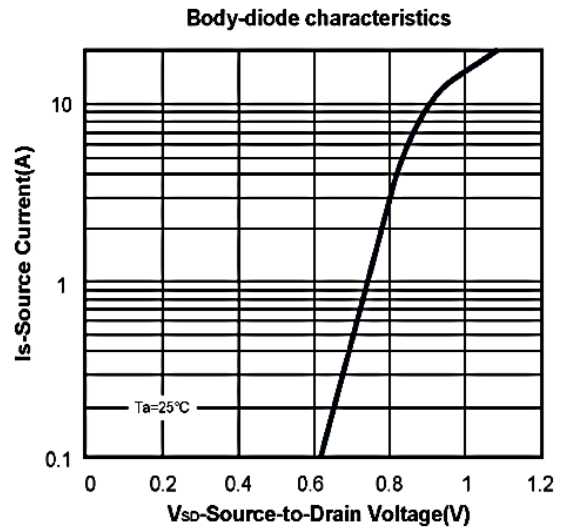
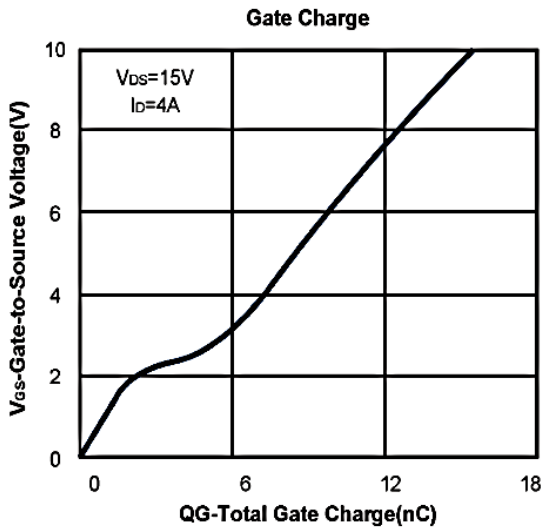
Threshold Voltage



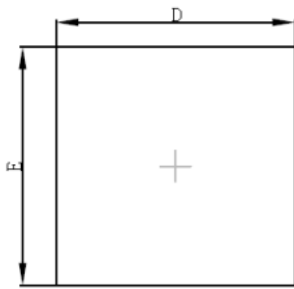
On-Region Characteristics



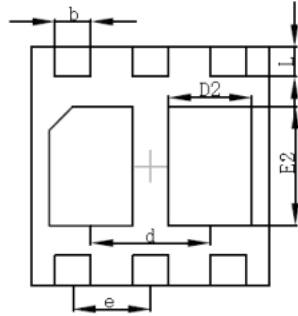
7. ELECTRICAL CHARACTERISTICS CURVES (Con.)



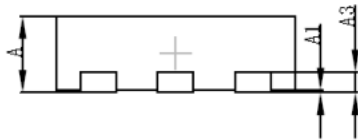
8. OUTLINE AND DIMENSIONS



TOP VIEW



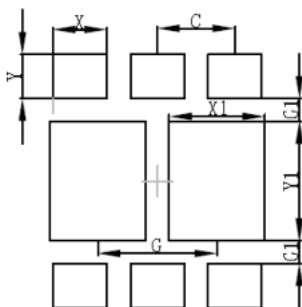
BOTTOM VIEW



SIDE VIEW

DFN2020 6D			
Dim	Min	Typ	Max
D	1.95	2.00	2.05
E	1.95	2.00	2.05
e	-	0.65	-
L	0.20	0.25	0.30
b	0.25	0.30	0.35
d	-	1.00	-
A	0.60	0.65	0.70
A1	0	0.02	0.05
A3	-	0.152	-
E2	0.95	1.00	1.05
D2	0.65	0.70	0.75
All Dimensions in mm			

9. SOLDERING FOOTPRINT



Dimensions	(mm)
X	0.45
Y	0.37
X1	0.80
Y1	1.00
C	0.65
G	1.00
G1	0.19

单击下面可查看定价，库存，交付和生命周期等信息

[>>LRC\(乐山无线电\)](#)